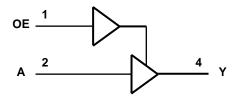


Pin Descriptions

Pin Name	Pin No.	Description
OE	1	Output Enable
A 2		Data Input
GND	3	Ground
Y 4		Data Output
V _{CC}	5	Supply Voltage

Logic Diagram



Function Table

Inp	Output	
OE	OE A	
Н	Н	Н
Н	L	L
L	Х	Z



Absolute Maximum Ratings (Note 2)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD CDM	Charged Device Model ESD Protection	1	K۷
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to 6.5	V
VI	Input Voltage Range	-0.5 to 6.5	V
Vo	Voltage applied to output in high or low state	-0.5 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I <0	-20	mA
l _{OK}	Output Clamp Current (V _O < 0 or V _O > V _{CC})	±20	mA
I _O	Continuous output current (V _O = 0 to V _{CC})	±25	mA
I _{CC}	Continuous current through V _{CC}	50	mA
I _{GND}	Continuous current through GND	-50	mA
TJ	Operating Junction Temperature	-40 to 150	°C
T _{STG}	Storage Temperature	-65 to 150	°C

Notes: 2. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

Recommended Operating Conditions (Note 3)

Symbol	Parameter	Min	Max	Unit
V _{CC}	Operating Voltage	4.5	5.5	V
V_{IH}	High-level Input Voltage	2.0		V
V _{IL}	Low-level input voltage		0.8	V
VI	Input Voltage	0	5.5	V
Vo	Output Voltage	0	V_{CC}	V
I _{OH}	High-level output current		-8	mA
I _{OL}	Low-level output current		8	mA
Δt/ΔV	Input transition rise or fall rate		20	ns/V
T _A	Operating free-air temperature	-40	125	°C

Notes: 3. Unused inputs should be held at V_{CC} or Ground.



Electrical Characteristics

0	D	25°C		25°C	-40°C to 85°C			-40°C to 125°C		11.24	
Symbol	Parameter	Test Conditions	V _{CC}	Min	Тур.	Max	Min	Max	Min	Max	Unit
.,	High Level	$I_{OH} = -50\mu A$	4.5V	4.4	4.5		4.4		4.4		
V_{OH}	Output Voltage	$I_{OH} = -8mA$	4.5V	3.94			3.8		3.70		V
	Low Level	$I_{OL} = 50\mu A$	4.5V		0	0.1		0.1		0.1	V
V _{OL}	Output Voltage	$I_{OL} = 8mA$	4.5V			0.36		0.44		0.55	V
l _l	Input Current	$V_I = 5.5V$ or GND	0 to 5.5V			± 0.1		± 1		± 2	μΑ
I _{OZ}	Z State Leakage Current	V _O =0 to 5.5V	5.5V			0.25		2.5		10	μΑ
I _{CC}	Supply Current	$V_I = 5.5V$ or GND $I_O=0$	5.5V			1		10		40	μΑ
C _i	Input Capacitance	$V_I = V_{CC} - or$ GND	5.5V		2.0	10		10		10	pF
ΔI _{CC}	Additional Supply Current	One input at 3.4 V Other inputs at V _{CC} or GND	5.5V			1.35		1.5			mA
0	Thermal Resistance	SOT25	(N. 1. 4.)		204						90.00
ӨЈА	θ _{JA} Junction-to- Ambient	SOT353	(Note 4)		371						°C/W
0	Thermal Resistance	SOT25	(Nlata 4)		52						°C // /
θ_{JC}	Junction-to- Case	SOT353	(Note 4)		143						°C/W

Note: 4. Test conditions for SOT25, and SOT353: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



Switching Characteristics

 $V_{CC} = 5V \pm 0.5V$ (see Figure 1)

Porcesson From TO			25°C		-40°C to 85°C		-40°C to 125°C		Unit		
Parameter	(Input)	(OUTPUT)		Min	Тур.	Max	Min	Max	Min	Max	Unit
	۸	V	C _L =15pF	0.6	3.4	5.5	0.6	6.5	0.6	7.0	ns
t _{pd}	AY	Ĭ	C _L =50pF	0.6	4.7	7.5	0.6	8.5	0.6	9.5	ns
	4 05	V	C _L =15pF	0.6	3.6	5.6	0.6	6.3	0.6	6.5	ns
t _{en}	OE	Y	C _L =50pF	0.6	5.4	8.0	0.6	9.0	0.6	9.0	ns
4	OF V	٧	C _L =15pF	0.6	4.3	6.8	0.6	8.0	0.6	8.5	ns
t _{dis}	OE	ť	C _L =50pF	0.6	6.1	8.8	0.6	10.0	0.6	11.0	ns

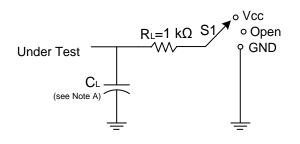
Operating Characteristics

 $T_A = 25$ °C

Parameter		Test Conditions	V _{CC} = 5 V Typ.	Unit
C _{pd}	Power dissipation capacitance	f = 1 MHz No Load	11	pF

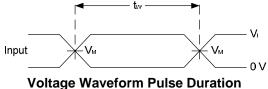


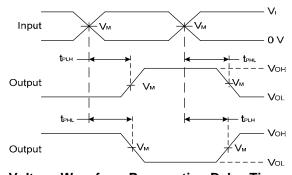
Parameter Measurement Information



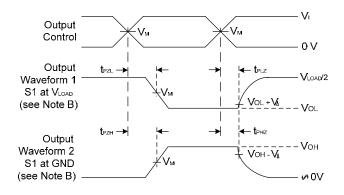
TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	Vload
t _{PHZ} /t _{PZH}	GND

Vac	In	puts	V	6	VA.	
Vcc	VI	t _r /t _f	V _M	CL	V Δ	
5V±0.5V	V_{CC}	≤3ns	V _{CC} /2	15pF	0.3V	
5V±0.5V	V_{CC}	≤3ns	V _{CC} /2	50pF	0.3V	





Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs



Voltage Waveform Enable and Disable Times Low and High Level Enabling

Figure 1. Load Circuit and Voltage Waveforms

A. Includes test lead and test apparatus capacitance.

- B. All pulses are supplied at pulse repetition rate ≤ 1 MHz.
- C. Inputs are measured separately one transition per measurement.
- D. tpLZ and tpHZ are the same as tdis.
- E. tpzL and tpzH are the same as teN
- F. tpLH and tpHL are the same as tpD.

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(P) (P)



SINGLE BUFFER GATE WITH 3-STATE OUTPUT

Ordering Information

Logic Device Function Package Packing
74 : Logic Prefix 126 : 3-State Buffer W5 : SOT25 7 : Tape & Reel

AHCT: 2 to 5.5V OE-High SE: SOT353

Family with TTL input level

1G: One gate

Device	Package	Packaging	7" Tape and Reel	
Device	Code	(Note 5)	Quantity	Part Number Suffix
74AHCT1G126W5-7	W5	SOT25	3000/Tape & Reel	-7
74AHCT1G126SE-7	SE	SOT353	3000/Tape & Reel	-7

Notes: 5. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

Marking Information

(Top View)

a~z: 27~52 week; z represents 52 and 53 week

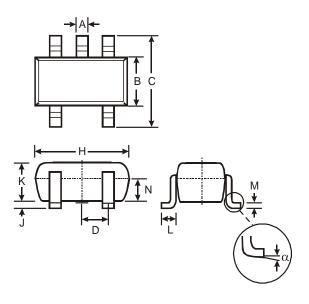
 $\underline{2}$ $\underline{3}$ \underline{X} : A $^{\sim}$ Z: Internal code

Part Number	Package	Identification Code
74AHCT1G126W5	SOT25	ZZ
74AHCT1G126SE	SOT353	ZZ



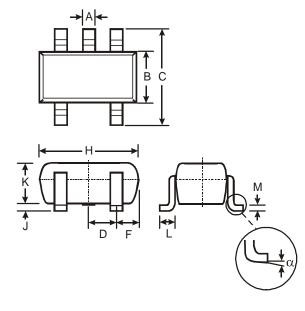
Package Outline Dimensions (All Dimensions in mm)

(1) Package Type: SOT25



	SOT25							
Dim	Min	Max	Тур					
Α	0.35	0.50	0.38					
В	1.50	1.70	1.60					
C	2.70	3.00	2.80					
D			0.95					
Н	2.90	3.10	3.00					
J	0.013	0.10	0.05					
K	1.00	1.30	1.10					
L	0.35	0.55	0.40					
М	0.10	0.20	0.15					
Z	0.70	0.80	0.75					
α	0°	8°	_					
All D	imensi	ons in	mm					

(2) Package Type: SOT353



SOT353		
Dim	Min	Max
Α	0.10	0.30
В	1.15	1.35
O	2.00	2.20
D	0.65 Typ	
F	0.40	0.45
H	1.80	2.20
J	0	0.10
K	0.90	1.00
L	0.25	0.40
М	0.10	0.22
α	0°	8°
All Dimensions in mm		



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